Customer Information Notification 201607003I

Issue Date: 09-Nov-2016
Effective Date: 09-Dec-2016

Management Summary

NXP Semiconductors announces an assembly backend process flow change on xQFP / SOIC / TSSOP packages at NXP-ATTJ assembly site, Tianjin, China.

Change Category

☐ Wafer Fab Process
☐ Wafer Fab Materials
☐ Wafer Fab Location
☑ Assembly Process
☐ Assembly Materials
☐ Assembly Location
☐ Product Marking
☐ Mechanical Specification
☐ Packing/Shipping/Labeling
☐ Test Location
☐ Test Process
☐ Test Equipment
☐ Design
☐ Errata
☐ Electrical spec./Test coverage

Assembly Backend Process Flow Change at ATTJ on xQFP / SOIC / TSSOP Packages

Information Notification

NXP Semiconductors announces an assembly backend process flow change on xQFP / SOIC / TSSOP packages at NXP-ATTJ assembly site, Tianjin, China. Process sequence change only for Plating and Dam-bar cutting operations. Change results in an observable visual difference with Dam-bar cut area now plated.

Current assembly backend process flow sequence:
Molding -> Marking -> PMC(Post Mold Cure) -> Plating -> Dam-bar cutting -> Forming & Separation -> FVI (Final Visual Inspection)

Proposed assembly backend process flow sequence:
Molding -> Marking -> PMC(Post Mold Cure) -> Dam-bar cutting -> Plating ->Forming & Separation -> FVI (Final Visual Inspection)

Why do we issue this Information Notification

The assembly backend process flow change can reduce compound particles induced during dam-bar cutting.

Identification of Affected Products

Product identification does not change

Impact

No change to form, fit, function or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Eric Bi
Position	Assembly Engineer
e-mail address	mailto:eric.bi@nxp.com?subject=Support

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands